

ABSTRACT

An array of caps is taught for protecting features on a semiconductor wafer. The array is fabricated by a novel method in which a two part mold is used. The array is made from a layer of thermoplastic material which is placed in the mold. Each cap in the array has a central portion and a perimeter wall. The mold is opened so that the array is carried by the first half. The array is applied to a wafer using the first half. After the arrays are applied, the wafer is separated into individual chips.

10